68. (canceled): A chip package comprising:

packaging material having a first side, an opposed second side, a third side disposed between the first side and the second side, and an opposed fourth side disposed between the first side and the second side; and

a lead extending from the first side of the packaging material,

a separate clip having a left connector portion, a right connector portion, and a bridge portion;

wherein in assembly

the left connector portion generally extends along the second side,
the right connector portion generally extends along the third side, and
the bridge portion generally extends along the fourth side, and
when the right connector portion and the left connector portion each
mate with a base, the clip helps retain the packaging material in contact with the
base by exerting a force on the fourth side.

69. (canceled): The chip package of claim 68, the packaging material having a third side, and further comprising a second clip portion extending from the third side of the packaging material.

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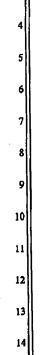
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70.	(previously amended): The chip package of claim 74, further comprising a
flexil	ble insert residing between the lead and the first side of the packaging
mate	rial, wherein the flexible insert supplies spring force when the lead is
com	pressed.

- (previously amended): The chip package of claim 70, wherein the flexible 71. insert is cylindrical.
- (previously added): The chip package of claim 71, wherein the flexible 72. insert is a compliant material.
- (previously added): The chip package of claim 72, wherein the compliant 73. material is an elastomer.
- (currently amended): The chip package of claim 6891, wherein the lead is 74. substantially C-shaped.
- (previously added): The chip package of claim 74, wherein the lead is *75.* compressible.
- (canceled): The chip package of claim 70, wherein the lead is compressible. 76.°
- (currently amended): The chip package of claim 6891, further comprising a 77. pin extending from the packaging material to guide the chip package in the base.

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78.	(canceled):	The chip package of claim 69	, wherein	the first	and second	clip
portio	ns are integr	al with the packaging material				

- (canceled): The chip package of claim 68, wherein the lead is a flexible 79. metallic material.
- (currently amended): The chip package of claim 7991, wherein the lead 80. metallic material comprises beryllium-copper.
- (currently amended): The chip package of claim 6891, wherein the 81. packaging material is comprised of a flexible material.
- (previously added): The chip package of claim 81, wherein the flexible 82. material supplies spring force when the lead is compressed.
- (currently amended): The chip package of claim 6891, wherein the 83. packaging material comprises silicone rubber.
- (canceled): The chip package of claim 68, further comprising a cam 84. follower extending from the packaging material.
- (currently amended): The chip package of claim 6891, further comprising 85. an integrated circuit disposed in the packaging material.

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86.	(currently amended):	The chip package of claim 6891,	wherein the chip is
flexib	le.		

- (canceled): The chip package of claim 68, wherein the packaging material 87. has a bottom-facing housing that extends laterally from the packaging material, the bottom-facing housing having a pocket formed therein.
- (canceled): The chip package of claim 87, wherein an end of the lead is 88. disposed within the pocket when the lead is compressed.
- 89. (withdrawn): A package, comprising: an integrated circuit enclosed with the package, substantially C-shaped leads at a first end of the package, a guide member on a side of the package, wherein the guide member has a ramp, and

mechanical support pins at a second end of the package opposite the first end,

wherein the package resides substantially horizontally with respect to a circuit board when the package is inserted in a base assembly coupled to the circuit board.

(withdrawn): The package of claim 89, wherein the integrated circuit is a 90. dynamic random access memory device.

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91.	(new): A chip package comprising:				
	packaging material having a first side;				
	a flexible lead extending from the first side; and				
	a clip extending from the packaging material.				

- 92. (new): The chip package of claim 70, wherein the lead is compressible.
- 93. (new): The chip package of claim 74 furthermore comprising an indentation; and wherein the lead extends into the indentation.
- 94. (new): The chip package of claim 74 furthermore comprising an indentation; and wherein the lead extends into the indentation when the lead is compressed.
- 95. (new): The chip package of claim 91, wherein the clip is integral with the packaging material.
- 96. (new): The chip package of claim 91, wherein the chip package is an assembly that comprises the clip and the packaging material, the clip and the packaging material each being separate from the other.
- 97. (new): A system comprising the chip package of claim 68 and a base unit, the base unit comprising a slotted guide; and the chip package further comprising a pin configured to be received by the slotted guide.